LOW-PROFILE GROUND PLANE

Q STRIP® HIGH-SPEED INTERCONNECTS

- Choice of pitch: 0.50 mm, 0.635 mm and 0.80 mm
- Integral ground plane rated to 25 A
- 5 – 25 mm stack heights
- Reliable signal integrity performance
- Mating/alignment “friendly” Blade and Beam contact system
- 40 – 180 signal pins / 28 – 120 differential pairs
- Right-angle and edge mount available
- 38 AWG micro coax and 30 AWG twinax cable assemblies rated to 14 Gbps
- Rugged guide post, weld tab and solder pin options
- Compatible with UMPT/UMPS micro power system for power/signal flexibility

INTEGRAL GROUND PLANE

- Surface mount ground plane between two signal rows improves electrical performance
- Significantly reduces row-to-row crosstalk
- Reduces coupling between pins within a row

SYSTEM

- QTH/QSH – 0.50 mm Pitch Header & Socket
- QTS/QSS – 0.635 mm Pitch Header & Socket
- QTE/QSE – 0.80 mm Pitch Header & Socket
- HQCD/EQCD – 0.50 mm & 0.80 mm Pitch Micro Coax Cable Assemblies
- HQDP/EQDP – 0.50 mm & 0.80 mm Pitch Twinax Cable Assemblies

For more High-Speed Board-to-Board Solutions, please visit samtec.com/mezzanine

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